Panasonic

XP05554

Silicon NPN epitaxial planar type

For high-speed switching

■ Features

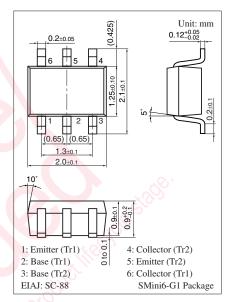
- Two elements incorporated into one package
- ullet Low collector-emitter saturation voltage $V_{CE(sat)}$

■ Basic Part Number

• 2SC3757 × 2

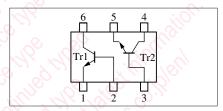
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	40	V	
Collector-emitter voltage (E-B short)	V _{CES}	40	V	
Emitter-base voltage (Collector open)	$V_{\rm EBO}$	5	V	
Collector current	I_{C}	100	mA	
Peak collector current	I_{CP}	300	mA	
Total power dissipation	P _T	150	mW	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: HE

Internal Connection

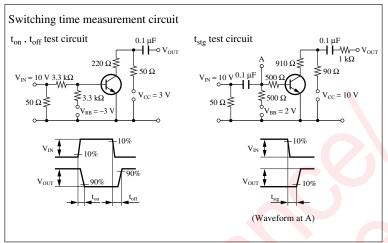


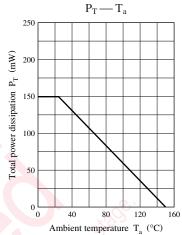
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

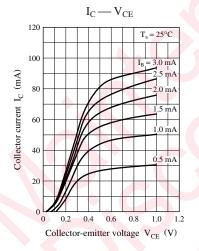
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 15 \text{ V}, I_{E} = 0$			0.1	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 4 \text{ V}, I_C = 0$			0.1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 1 \text{ V}, I_{C} = 10 \text{ mA}$	90		200	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$		0.17	0.25	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$			1.0	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$		450		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2	6	pF
(Common base, input open circuited)						
Turn-on time	t _{on}	Refer to the switching time measurement		17		ns
Turn-off time	t _{off}	circuit		17		ns
Storage time	t _{stg}			10		ns

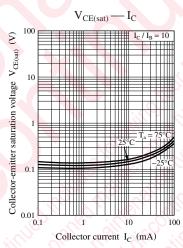
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

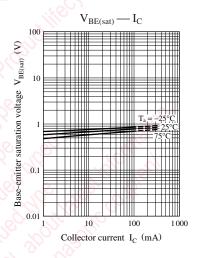
Panasonic

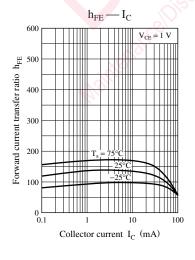


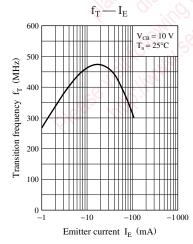


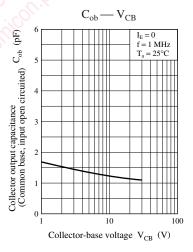












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